

SURFACE MOUNT ULTRAFAST RECOVERY RECTIFIER

FEATURES:

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

Circuit Diagram & Pin Configuration:



SMAF



Marking

Type number	Marking code
US1AF	US1A
US1BF	US1B
US1DF	US1D
US1GF	US1G
US1JF	US1J
US1KF	US1K
US1MF	US1M

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	US1AF	US1BF	US1DF	US1GF	US1JF	US1KF	US1MF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T _c = 125 °C	I _{F(AV)}	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I _{FSM}	30							A
Maximum Instantaneous Forward Voltage at 1 A	V _F	1.0			1.3	1.65			V
Maximum DC Reverse Current T _a = 25 °C at Rated DC Blocking Voltage T _a =125 °C	I _R	5 100							μA
Maximum Reverse Recovery Time ⁽¹⁾	t _{rr}	50				75			ns
Typical Junction Capacitance ⁽²⁾	C _j	15							pF
Typical Thermal Resistance ⁽³⁾	R _{θJA}	80							°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150							°C

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(3) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

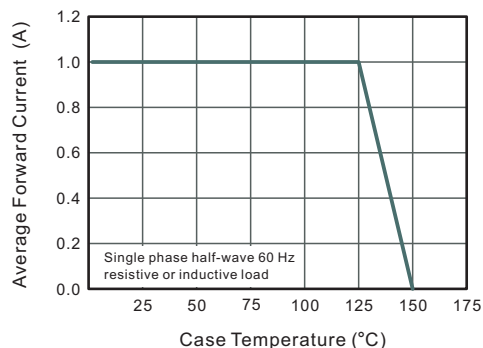


Fig.2 Typical Reverse Characteristics

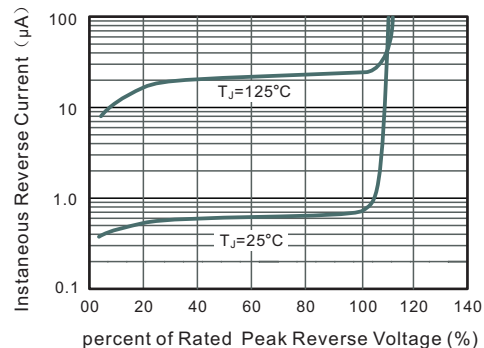


Fig.3 Typical Forward Characteristics

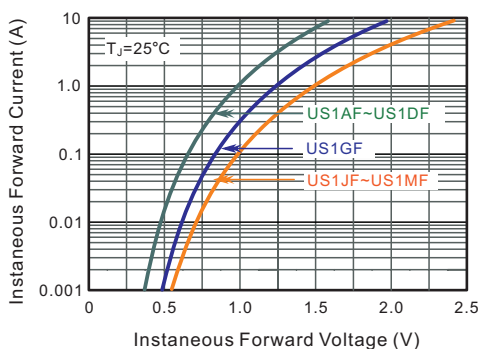


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

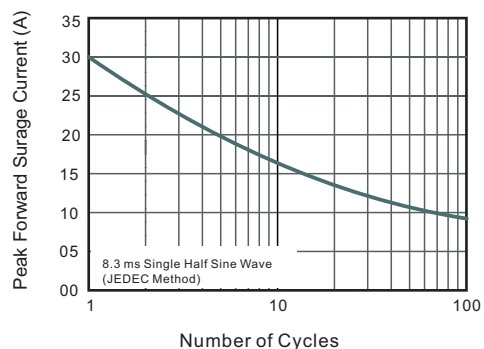
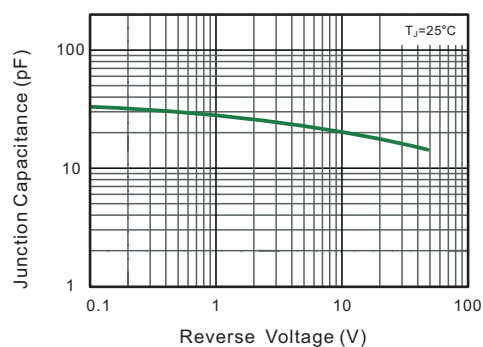


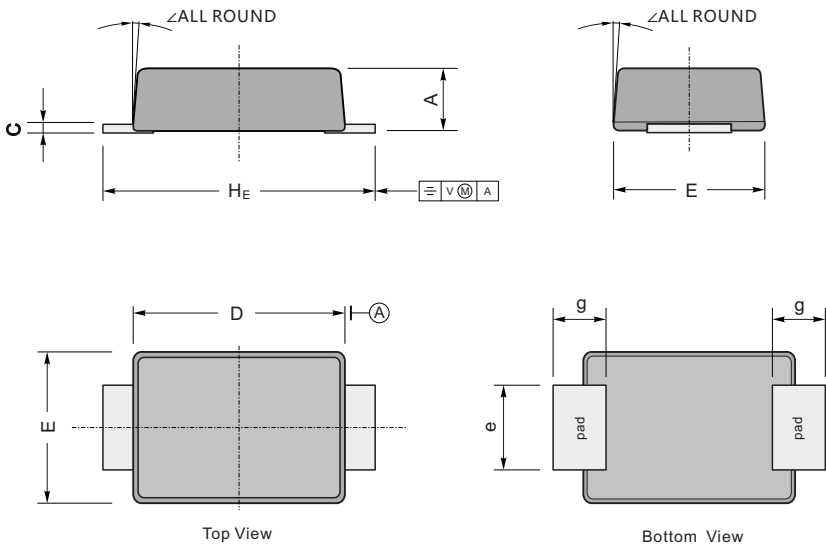
Fig.5 Typical Junction Capacitance



PACKAGE OUTLINE

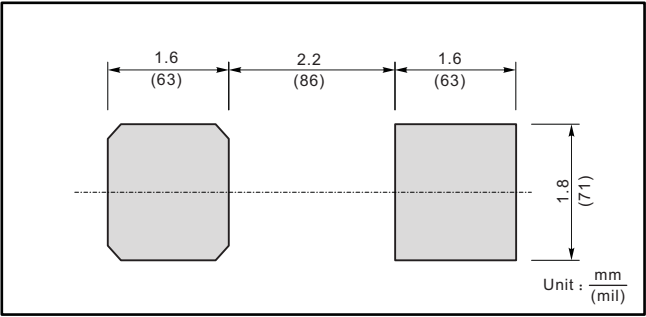
Plastic surface mounted package; 2 leads

SMAF



UNIT		A	C	D	E	e	g	H _E	\angle
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size



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